

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.
A	BC-10-0100061	Herry Yang
B	BC-11-0038722	Herry Yang
C	BC-11-0049137	Herry Yang
D	BC-11-0119946	Herry Yang
E	BC-13-0004440	C.S Li
F	BC-13-0087027	C.S Li

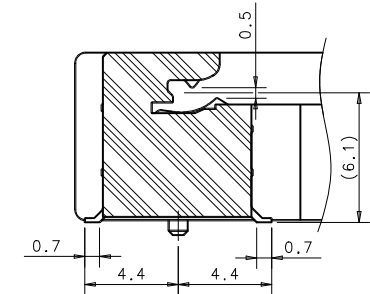
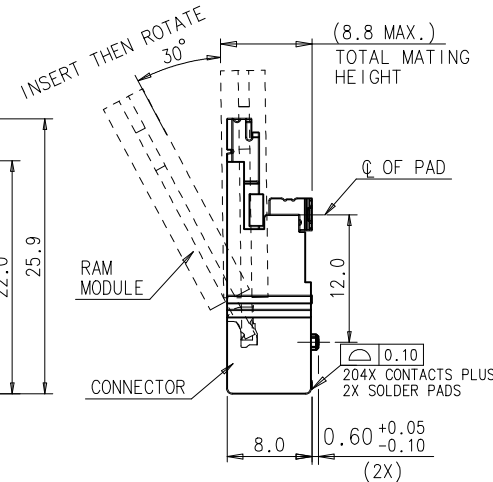
NOTES:

- ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
(PER PIN) DOESN'T EXCEED 30°C ABOVE AMBIENT AT 0.5 AMPERE MAX. PER PIN.
 - VOLTAGE RATING: 25V AC.
 - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
 - CONTACT RESISTANCE: 50 MILLIOHMS MAX. PER PIN INITIAL.
60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.
- MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
- OPERATION TEMPERATURE: -55°C TO +85°C.
- RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260°C, 10~20S.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.

PART NO. DESCRIPTION: A S O A6 2 * - H 8 S N - * H

MEMORY MODULE SOCKET
HORIZONTAL TYPE
SINGLE ROW
NO. OF POS.
A6 = 204 POS.
SMT
CONTACT AREA PLATING
1=GOLD FLASH
Y=5u" GOLD PLATING
6=10u" GOLD PLATING
7=15u" GOLD PLATING
3=30u" GOLD PLATING

H=HALOGEN FREE & LEAD FREE
4=SOFT TRAY
7=TAPE REEL
N=GENERAL TYPE
S=STANDARD
8=8.0mm HEIGHT
DDR III SO DIMM



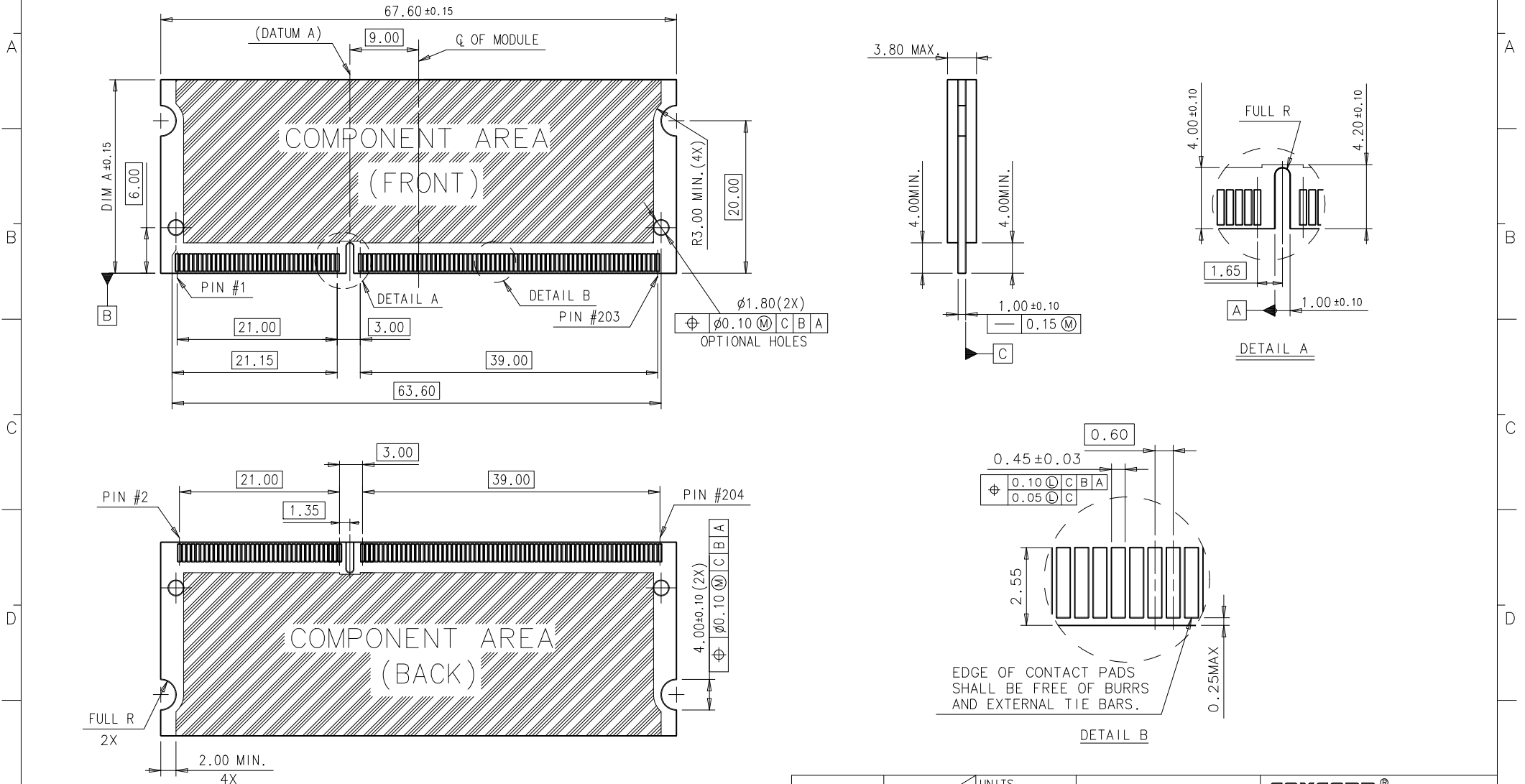
SECTION A-A

ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
④	METAL PAD	2	COPPER ALLOY	50u" NICKEL UNDER PLATING OVER ALL 2u" Pd PLATING OVER SOLDER AREA
③	METAL SPRING	2	COPPER ALLOY	50u" NICKEL PLATING OVER ALL
②	CONTACT	204	COPPER ALLOY	50u" NICKEL UNDER PLATING GOLD FLASH AT TAIL GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN-FREE, IVORY COLOR

X.	± 0.30	X°	±	UNITS	mm	NAME (INTENDED USE)	FOXCONN®
.X	± 0.25	.X°	±	MAT'L		DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX	± 0.15	.XX°	±			PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX	±	.XXX°	±	FINISH		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.						APPD: C.S Li	DWG NO.: 317-0000-1996
						CHKD: ZH Wang	SCALE SHEET REV.
						DR: Wang Justin 3/5/14	N/A 1/5 H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



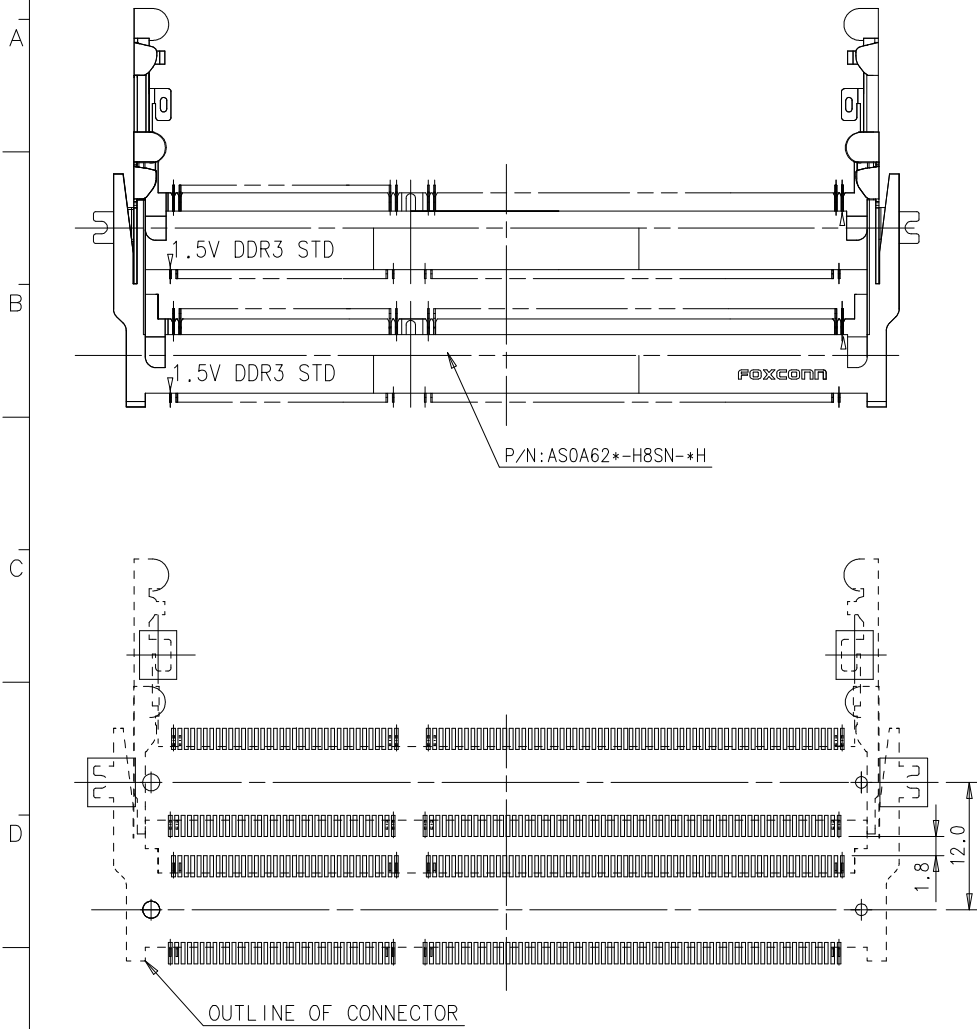
DDRIII SO-DIMM MODULE BOARD LAYOUT

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN®
.X ± 0.10	.X° ±	MAT'L	DDRIII SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±	Q'TY	AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				DWG NO.:
APPD: C.S Li				317-0000-1996
CHKD: ZH Wang				SCALE SHEET REV.
DR: Wang Jusrin 3/5/14				N/A 2/5 H

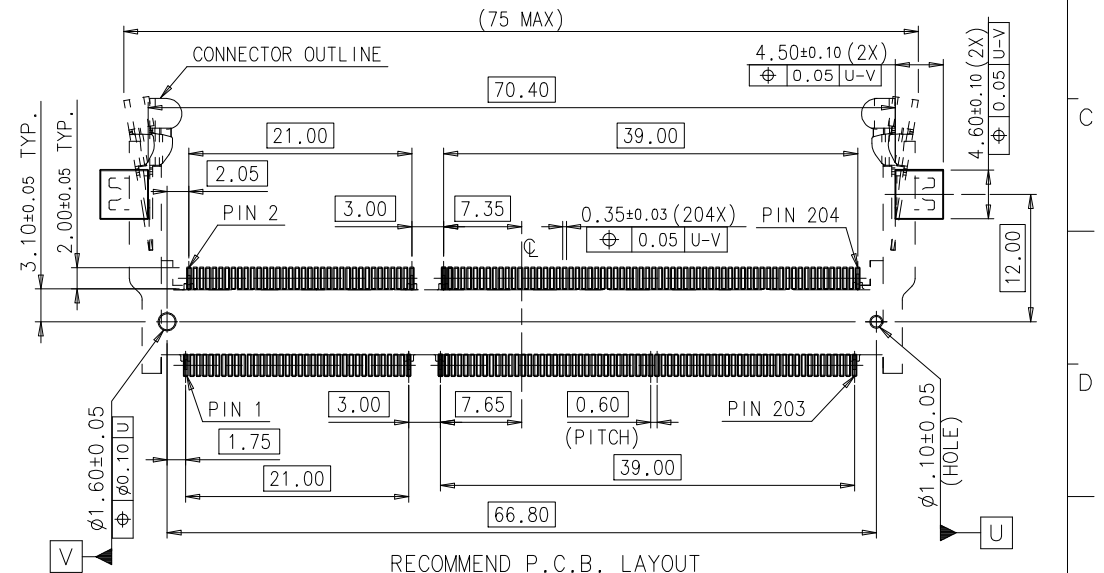
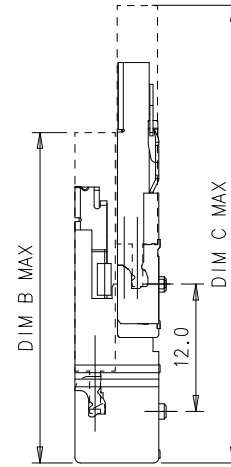
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



P.C.B. LAYOUT (STACKED ORIENTATION)

SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

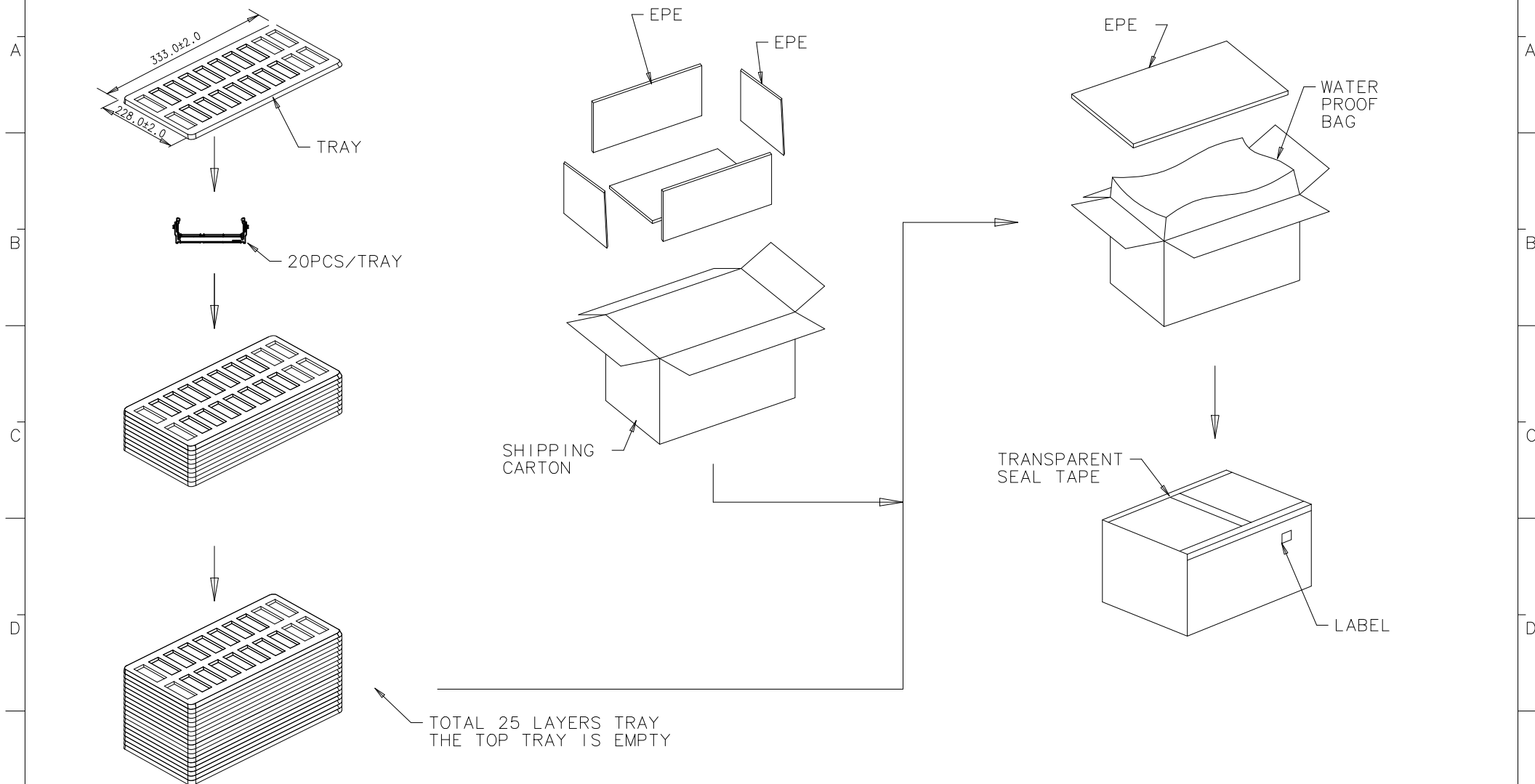


RECOMMEND P.C.B. LAYOUT

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN®
.X ± 0.10	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±	Q'TY	AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: C.S Li	DWG NO.:
			CHKD: ZH Wang	317-0000-1996
			DR: Wang Justin 3/5/14	SCALE SHEET REV. N/A 3/5 H

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



NOTES:

1. PACKING CAPACITY : 20 PCS/TRAY, 24 TRAYS/BOX,
TOTAL 480 PCS/BOX.

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X° ±	MAT'L	DDRIII SO DIMM CONNECTOR	
.XX ± 0.5	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: ☐ CONFIDENTIAL ☐ SECRET ☒ GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8SN-*H	TITLE: CUSTOMER DRAWING
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED, AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		Q'TY	APPD: C.S Li	DWG NO.: 317-0000-1996
			CHKD: ZH Wang	 SCALE SHEET REV. N/A 4/5 H
			DR: Wang Justin 3/5/14	

CONNECTOR P/N

AS0A62*-H8SN-4H

